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PAGE 01/10

FACSIMILE COVER SHEET

Date:	April 24, 2006	Fax:	571-273-8300
To:	U.S. Patent and Trademark Office	Phone:	

Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450

From: David C. Hsia Serial No.: 10/826,800 **Docket:** 10030280-4

Pages: 10 (including cover sheet)

4083820481

Message:

Re:

Re:

Applicant(s):

Tanya J. Snyder, Robert H. Yi, Robert E. Wilson

Assignee:

Agilent Technologies, Inc.

Amendment in response to Office Action

Title:

Wafer Bonding Using Reactive Foils for Massively Parallel

Micro-Electromechanical Systems Packaging

Serial No.:

10/826,800

Examiner: Docket No.: David Nhu

Filed: April 15, 2004

10030280-4

Group Art Unit: 2818

Dear Sir:

Transmitted herewith are the following documents in the above-identified application:

- (1) Transmittal Letter (1 page);
- (2) Amendment (7 pages).

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04/24/2006 19:00

AVAGO TECHNOLOGIES, LTD. P.O. Box 1920 Denver, Colorado 80201-1920

ATTORNEY DOCKET NO. 10030280-4

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APR 2 4 2006

Inventor(s): Tanya J. Snyder et al.

Serial No.:

10/826,800

Examiner: David Nhu

Filing Date: April 15, 2004

4083820481

Group Art Unit: 2818

Title: WAFER BONDING USING REACTIVE FOILS FOR MASSIVELY PARALLEL

MICRO-ELECTROMECHANICAL SYSTEMS PACKAGING

COMMISSIONER FOR PATENTS

P.O. Box 1450

Alexandria VA 22313-1450

SIr:		, TRAI	NSMITTAL I	LETTER FOR RESPONS	E/AMENDME	NT				
Tra	nsmitted h	erewith is/are the follo	wing in the	above-identified applie	cation:					
×	Response/Amendment				Petition to extend time to res					
	New fee	as calculated below	☐ Supp	Supplemental Dec						
	No additional fee (Address envelope to "Mail Stop Amendments")									
	Other:				(Fee \$)				
-		CLAIMS	AS AMENDE	D BY OTHER THAN A SM	ALL ENTITY		· · · · · · · · · · · · · · · · · · ·			
	(1) FOR	(2) CLAIMS REMAINING AFTER AMENDMENT	(3) NUMBER EXTRA	(4) HIGHEST NUMBER PREVIOUSLY PAID FOR	(5) PRESENT	(6) RATE	(7) ADDITIO			

	CLAIMS	AS AMEND	ED BY OTHER THAN A SMA	LLI	ENTITY				
(1) FOR	(2) CLAIMS REMAINING AFTER AMENDMENT	(3) NUMBER EXTRA	(4) HIGHEST NUMBER PREVIOUSLY PAID FOR	PF	(5) RESENT EXTRA	F	(6) RATE	(7) ADDITIONAL FEES	
TOTAL CLAIMS	6	MINUS	20	=	0	×	50	\$	0
INDEP. CLAIMS	4	MINUS	3	=	1	х	200	\$	200
FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM +.360					\$	0			
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							FEES	5	0
			TOTAL ADDITIONAL FEE F	OR	THIS AM	END	MENT	\$	200

Charge \$200 to Deposit Account 50-3718. At any time during the pendency of this application, please charge any fees required or credit any over payment to Deposit Account 50-3718 pursuant to 37 CFR 1.2 5. Additionally please charge any fees to Deposit Account 50-3718 under 37 CFR 1.16, 1.17, 1.19, 1.20 and 1.21. A duplicate copy of this transmittal letter is enclosed.

I hereby certify that this paper is being facsimile transmitted to the Patent and Trademark Office on the date shown below:

Date of facsimile: April 24, 2008

Typed Name: David C. Hols

Signature:

Respectfully submitted. Tanya J. Snyder et al. Ву

David C. Hsia

Attorney/Agent for Applicant(s)

Reg. No. 46,235

Date: April 24, 2006

Telephone No. (408) 382-0480

Rev 10/04 (TransAms)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Applicant(s):

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Docket No .:

10030280-4

San Jose, California April 24, 2006

Mail Stop Amendment Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450

<u>AMENDMENT</u>

Dear Sir:

This is a response to the January 24, 2006 Office Action, which has a statutorily shortened period for response that ends on April 24, 2006. Please amend the above-identified application as follows:

Amendments to the Abstract begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper,

Remarks begin on page 5 of this paper.

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